

#### **Features**

■ Low Offset Voltage: 150µV Maximum

■ Low Drift: ±0.9µV/°C

Wide Supply Range: 2.7V to 36VGain-bandwidth Product: 7MHz

■ High Slew Rate: 20V/µs

■ High EMIRR: 84dB at 900MHz

High Common-Mode Rejection: 126dB
High Power Supply Rejection: 130dB
Low Input Bias Current: 3pA Typical

■ Below-Ground (V-) Input Capability to -0.3V

■ Rail-to-Rail Output Voltage Range

■ Pb-Free Packages are Available

■ -40°C to 125°C Operation Range

Robust 3kV – HBM and 2kV – CDM ESD Rating

#### **Applications**

- Transducer Amplifier
- Bridge Amplifier
- Photodiode Pre-amp
- I/V Converter
- Temperature Measurements
- Strain Gage Amplifier
- Medical Instrumentation

#### **Description**

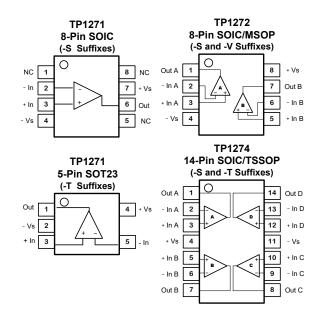
The TP1271/TP1272/TP1274 series are Precision EMI Hardened, high-voltage CMOS op-amps featuring EMIRR of 84dB at 900MHz. TP127X series op amps could operate from  $\pm 1.35$ V to  $\pm 18$ V supplies with excellent performance, They offer very low offset voltage and drift, low bias current, high common-mode rejection, and high power supply rejection.

The TP127X are unity gain stable with 100pF capacitive load with a wide 7MHz bandwidth, 20V/µs high slew rate, which makes the device appropriate for I/V converters.

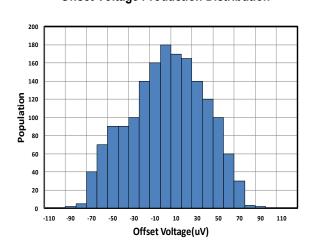
These op amps are ideal for various applications, including process control, industrial and instrumentation equipment, active filtering, data conversion, buffering, and power control and monitoring. Additionally, the TP127X is EMI hardened to minimize any interference, so they are ideal for EMI sensitive application.

The TP1271 is single channel version available in 8-pin SOIC and 5-pin SOT23 package. The TP1272 is dual channel version available in 8-pin SOIC and MSOP package. The TP1274 is quad channel version available in 14-pin SOIC and TSSOP package.

### Pin Configuration (Top View)



#### Offset Voltage Production Distribution



<sup>4 3</sup>PEAK and the 3PEAK logo are registered trademarks of 3PEAK INCORPORATED. All other trademarks are the property of their respective owners.

#### **Order Information**

Model Name	Order Number	Package	Transport Media, Quantity	Marking Information
TP1271	TP1271-SR	8-Pin SOIC	Tape and Reel, 4,000	TP1271
	TP1271-TR	5-Pin SOT23	Tape and Reel, 3,000	D12T
TP1272	TP1272-SR	8-Pin SOIC	Tape and Reel, 4,000	TP1272
	TP1272-VR	8-Pin MSOP	Tape and Reel, 3,000	TP1272
TP1274	TP1274-SR	14-Pin SOIC	Tape and Reel, 2,500	TP1274
	TP1274-TR	14-Pin TSSOP	Tape and Reel, 3,000	TP1274

#### **Absolute Maximum Ratings Note 1**

Supply Voltage: V <sup>+</sup> – V <sup>-</sup> Note 240.0V	Operating Temperature Range40°C to 125°C
Input VoltageV <sup>-</sup> – 0.3 to V <sup>+</sup> + 0.3	Maximum Junction Temperature 150°C
Input Current: +IN, -IN Note 3 ±20mA	Storage Temperature Range –65°C to 150°C
Output Short-Circuit Duration Note 4 Indefinite	Lead Temperature (Soldering, 10 sec) 260°C
Current at Supply Pins ±60mA	

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: The op amp supplies must be established simultaneously, with, or before, the application of any input signals.

**Note 3:** The inputs are protected by ESD protection diodes to each power supply. If the input extends more than 500mV beyond the power supply, the input current should be limited to less than 10mA.

**Note 4**: A heat sink may be required to keep the junction temperature below the absolute maximum. This depends on the power supply voltage and how many amplifiers are shorted. Thermal resistance varies with the amount of PC board metal connected to the package. The specified values are for short traces connected to the leads.

#### **ESD, Electrostatic Discharge Protection**

Symbol	Parameter	Condition	Minimum Level	Unit
HBM	Human Body Model ESD	MIL-STD-883H Method 3015.8	3	kV
CDM	Charged Device Model ESD	JEDEC-EIA/JESD22-C101E	2	kV

#### Thermal Risistance

Package Type	$\theta_{JA}$	$\theta_{ extsf{JC}}$	Unit
5-Pin SOT23	250	81	°C/W
8-Pin SOIC	158	43	°C/W
8-Pin MSOP	210	45	°C/W
14-Pin SOIC	120	36	°C/W
14-Pin TSSOP	180	35	°C/W

## 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Electrical Characteristics**

The specifications are at  $T_A$  = 27°C.  $V_{SUPPLY}$  =  $\pm$  15V,  $V_{CM}$  =  $V_{OUT}$  =0V,  $R_L$  =  $2k\Omega$ ,  $C_L$  =100pF.Unless otherwise noted.

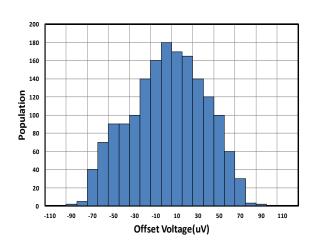
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Vos	Input Offset Voltage	$V_{CM} = V_{DD}/2$	-150	±50	+150	μV
Vos TC	Input Offset Voltage Drift	-40°C to 125°C		0.9		μV/°C
		T <sub>A</sub> = 27 °C		3		pA
l <sub>B</sub>	Input Bias Current	T <sub>A</sub> = 85 °C		250		pA
		T <sub>A</sub> = 125 °C		7.7		nA
los	Input Offset Current			0.001		pА
Vn	Input Voltage Noise	f = 0.1Hz to 10Hz		2.35		μV <sub>RMS</sub>
<b>e</b> n	Input Voltage Noise Density	f = 1kHz		19		nV/√Hz
C <sub>IN</sub>	Input Capacitance	Differential Common Mode		4 2.5		pF
CMRR	Common Mode Rejection Ratio	V <sub>CM</sub> = -14.6V to 13V		126		dB
V <sub>CM</sub>	Common-mode Input Voltage Range		V0.3		V+-2.0	V
PSRR	Power Supply Rejection Ratio			130		dB
A <sub>VOL</sub>	Open-Loop Large Signal Gain	$R_{LOAD} = 2k\Omega$	100	118		dB
V <sub>OL</sub> , V <sub>OH</sub>	Output Swing from Supply Rail	$R_{LOAD} = 100 k\Omega$		50		mV
Rout	Closed-Loop Output Impedance	G = 1, f =1kHz, I <sub>OUT</sub> = 0		0.01		Ω
Ro	Open-Loop Output Impedance	f = 1kHz, I <sub>OUT</sub> = 0		125		Ω
I <sub>SC</sub>	Output Short-Circuit Current	Sink or source current		80		mA
$V_{DD}$	Supply Voltage		2.7		36	V
ΙQ	Quiescent Current per Amplifier			900		μA
PM	Phase Margin	$R_{LOAD} = 2k\Omega$ , $C_{LOAD} = 100pF$		60		٥
GM	Gain Margin	$R_{LOAD} = 2k\Omega$ , $C_{LOAD} = 100pF$		8		dB
GBWP	Gain-Bandwidth Product	f = 1kHz		7		MHz
SR	Slew Rate	$A_V = 1$ , $V_{OUT} = 0V$ to $10V$ , $C_{LOAD} = 100pF$ , $R_{LOAD} = 2k\Omega$		20		V/µs
FPBW	Full Power Bandwidth Note 1			210		kHz
ts	Settling Time, 0.1% Settling Time, 0.01%	A <sub>V</sub> = -1, 10V Step		1		μs
THD+N	Total Harmonic Distortion and Noise	$f = 1kHz$ , $A_V = 1$ , $R_L = 2k\Omega$ , $V_{OUT} = 3.5V_{RMS}$		0.0001		%
X <sub>talk</sub>	Channel Separation	$f = 1kHz$ , $R_L = 2k\Omega$		110		dB

Note 1: Full power bandwidth is calculated from the slew rate FPBW =  $SR/\pi \cdot V_{P-P}$ 

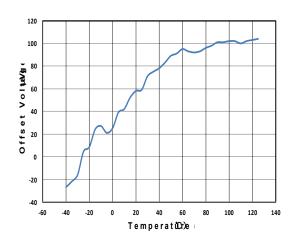
## 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Typical Performance Characteristics**

VS = ±15V, VCM = 0V, RL = Open, unless otherwise specified.

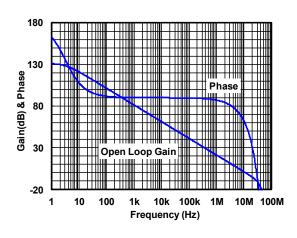
#### Offset Voltage Production Distribution



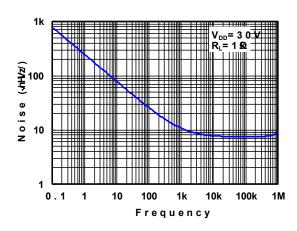
#### Offset Voltage vs. Temperature



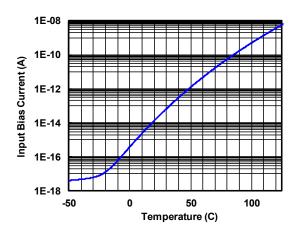
**Open-Loop Gain and Phase** 



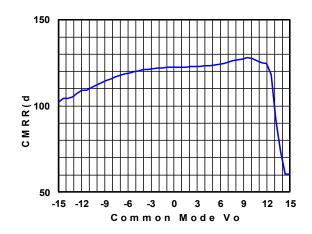
Input Voltage Noise Spectral Density



Input Bias Current vs. Temperature



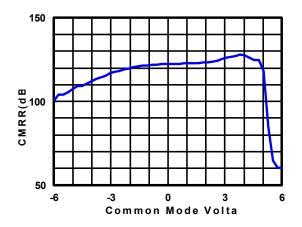
Input Bias Current vs. Input Common Mode Voltage



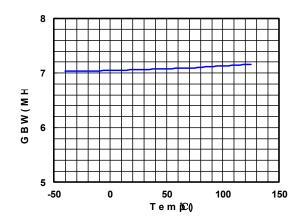
## 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Typical Performance Characteristics**

VS = ±15V, VCM = 0V, RL = Open, unless otherwise specified.(Continue)

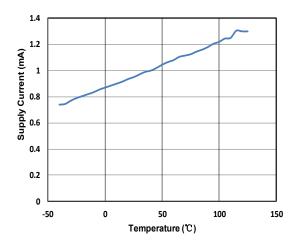
#### **Common Mode Rejection Ratio**



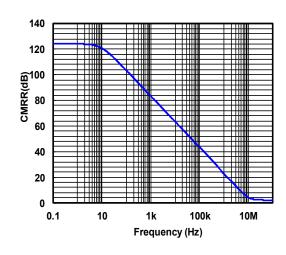
#### Unity Gain Bandwidth vs. Temperature



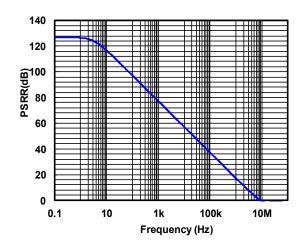
#### **Quiescent Current vs. Temperature**



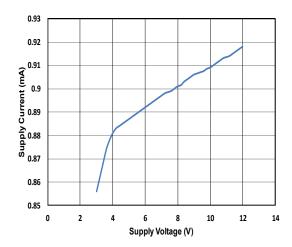
**CMRR vs. Frequency** 



#### **Power-Supply Rejection Ratio**



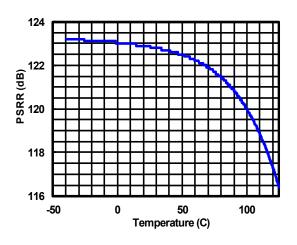
#### **Quiescent Current vs. Supply Voltage**



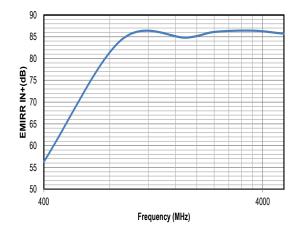
### 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Typical Performance Characteristics**

VS = ±15V, VCM = 0V, RL = Open, unless otherwise specified.(Continue)

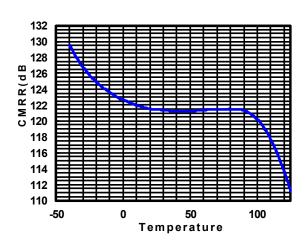
#### Power-Supply Rejection Ratio vs. Temperature



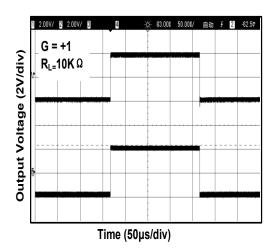
EMIRR IN+ vs. Frequency



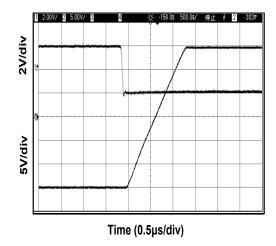
#### **CMRR vs. Temperature**



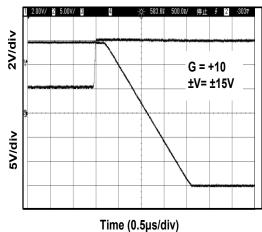
Large-Scale Step Response



#### **Negative Over-Voltage Recovery**



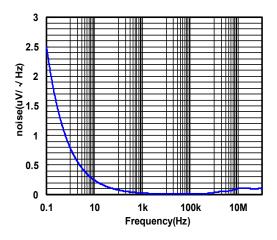
#### Positive Over-Voltage Recovery



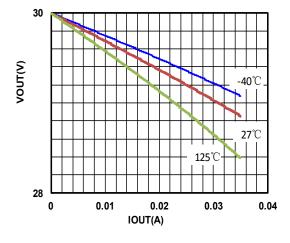
## 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Typical Performance Characteristics**

VS = ±15V, VCM = 0V, RL = Open, unless otherwise specified.(Continue)

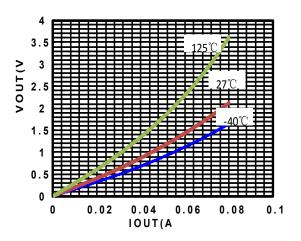
#### **Voltage Noise Spectral Density vs. Frequency**



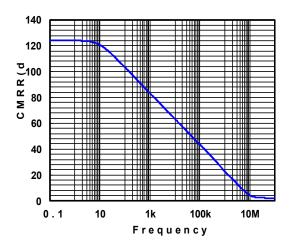
Positive Output Swing vs. Load Current



#### **Negative Output Swing vs. Load Current**



**CMRR vs. Frequency** 



#### TP1271 / TP1272 / TP1274

#### 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth

#### **Pin Functions**

**-IN:** Inverting Input of the Amplifier. Voltage range of this pin can go from  $V^-$  to  $(V^+ - 2.0V)$ .

**+IN:** Non-Inverting Input of Amplifier. This pin has the same voltage range as –IN.

V+ or +V<sub>s</sub>: Positive Power Supply. Typically the voltage is from 2.7V to 36V. Split supplies are possible as long as the voltage between V+ and V– is between 2.7V and 36V. A bypass capacitor of  $0.1\mu F$  as close to the part as possible should be used between power supply pins or between supply pins and ground.

**V** or  $^{\text{T}}$ **V**<sub>S</sub>: Negative Power Supply. It is normally tied to ground. It can also be tied to a voltage other than ground as long as the voltage between  $V^{+}$  and  $V^{-}$  is from 2.7V to 36V. If it is not connected to ground, bypass it

with a capacitor of  $0.1\mu F$  as close to the part as possible.

**OUT:** Amplifier Output. The voltage range extends to within milli-volts of each supply rail.

#### **Operation**

The TP127X have input signal range from V $^-$  to (V $^+$  – 2.0V). The output can extend all the way to the supply rails. The input stage is comprised of a PMOS differential amplifier. The Class-AB control buffer and output bias stage uses a proprietary compensation technique to take full advantage of the process technology to drive very high capacitive loads. This is evident from the transient over shoot measurement plots in the Typical Performance Characteristics.

#### **Applications Information**

#### **EMI Harden**

The EMI hardening makes the TP1271/1272/1274 a must for almost all op amp applications. Most applications are exposed to Radio Frequency (RF) signals such as the signals transmitted by mobile phones or wireless computer peripherals. The TP1271/1272/1274 will effectively reduce disturbances caused by RF signals to a level that will be hardly noticeable. This again reduces the need for additional filtering and shielding Using this EMI resistant series of op amps will thus reduce the number of components and space needed for applications that are affected by EMI, and will help applications, not yet identified as possible EMI sensitive, to be more robust for EMI.

#### Wide Supply Voltage

The TP1271/1272/1274 operational amplifiers can operate with power supply voltages from 2.7V to 36V. Each amplifier draws 0.9mA quiescent current at 36V supply voltage. The TP1271/1272/1274 is optimized for wide bandwidth low power applications. They have an industry leading high GBW to power ratio and the GBW remains nearly constant over specified temperature range.

#### **Low Input Bias Current**

The TP1271/1272/1274 is a CMOS OPA family and features very low input bias current in 3pA range. The low input bias current allows the amplifiers to be used in applications with high resistance sources. Care must be taken to minimize PCB Surface Leakage. See below section on "PCB Surface Leakage" for more details.

#### **PCB Surface Leakage**

In applications where low input bias current is critical, Printed Circuit Board (PCB) surface leakage effects need to be considered. Surface leakage is caused by humidity, dust or other contamination on the board. Under low humidity conditions, a typical resistance between nearby traces is  $10^{12}\Omega$ . A 5V difference would cause 5pA of current to flow,

which is greater than the TP1271/1272/1274 OPA's input bias current at +27°C (±3pA, typical). It is recommended to use multi-layer PCB layout and route the OPA's -IN and +IN signal under the PCB surface.

The effective way to reduce surface leakage is to use a guard ring around sensitive pins (or traces). The guard ring is biased at the same voltage as the sensitive pin. An example of this type of layout is shown in Figure 2 for Inverting Gain application.

- 1. For Non-Inverting Gain and Unity-Gain Buffer:
  - a) Connect the non-inverting pin (V<sub>IN</sub>+) to the input with a wire that does not touch the PCB surface.
  - b) Connect the guard ring to the inverting input pin (V<sub>IN</sub>-). This biases the guard ring to the Common Mode input voltage.
- 2. For Inverting Gain and Trans-impedance Gain Amplifiers (convert current to voltage, such as photo detectors):
  - a) Connect the guard ring to the non-inverting input pin  $(V_{IN}+)$ . This biases the guard ring to the same reference voltage as the op-amp (e.g.,  $V_{DD}/2$  or ground).
  - b) Connect the inverting pin (V<sub>IN</sub>-) to the input with a wire that does not touch the PCB surface.

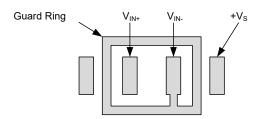


Figure 2 The Layout of Guard Ring

#### **Ground Sensing and Rail to Rail Output**

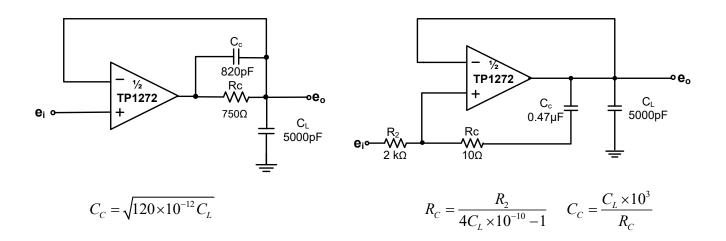
The TP1271/1272/1274 family has excellent output drive capability. It drives  $2k\Omega$  load directly with good THD performance. The output stage is a rail-to-rail topology that is capable of swinging to within 50mV of either rail.

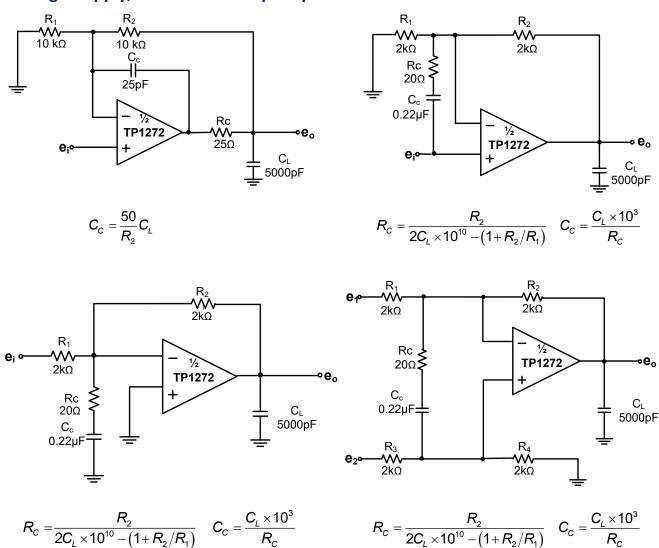
The maximum output current is a function of total supply voltage. As the supply voltage to the amplifier increases, the output current capability also increases. Attention must be paid to keep the junction temperature of the IC below 150°C when the output is in continuous short-circuit. The output of the amplifier has reverse-biased ESD diodes connected to each supply. The output should not be forced more than 0.3V beyond either supply, otherwise current will flow through these diodes.

#### **Driving Large Capacitive Load**

The TP1271/1272/1274 op-amp family is designed to drive large capacitive loads. As always, larger load capacitance decreases overall phase margin in a feedback system where internal frequency compensation is utilized. As the load capacitance increases, the feedback loop's phase margin decreases, and the closed-loop bandwidth is reduced. This produces gain peaking in the frequency response, with overshoot and ringing in output step response. The unity-gain buffer (G = +1V/V) is the most sensitive to large capacitive loads.

When driving large capacitive loads with the TP1271/1272/1274 op-amp family (e.g., > 1,000 pF), different compensation schemes (Figure 3) improve the feedback loop's phase margin and stability.





NOTE: Design equations and component values are approximate, User adjustment is required for optimum performance.

Figure 3 Driving Large Capacitive Loads

#### **Power Supply Layout and Bypass**

The TP1271/1272/1274 OPA's power supply pin ( $V_{DD}$  for single-supply) should have a local bypass capacitor (i.e., 0.01 $\mu$ F to 0.1 $\mu$ F) within 2mm for good high frequency performance. It can also use a bulk capacitor (i.e., 1 $\mu$ F or larger) within 100mm to provide large, slow currents. This bulk capacitor can be shared with other analog parts.

Ground layout improves performance by decreasing the amount of stray capacitance and noise at the OPA's inputs and outputs. To decrease stray capacitance, minimize PC board lengths and resistor leads, and place external components as close to the op amps' pins as possible.

#### **Proper Board Layout**

To ensure optimum performance at the PCB level, care must be taken in the design of the board layout. To avoid leakage currents, the surface of the board should be kept clean and free of moisture. Coating the surface creates a barrier to moisture accumulation and helps reduce parasitic resistance on the board.

Keeping supply traces short and properly bypassing the power supplies minimizes power supply disturbances due to output current variation, such as when driving an ac signal into a heavy load. Bypass capacitors should be connected as closely as possible to the device supply pins. Stray capacitances are a concern at the outputs and the inputs of the amplifier. It is recommended that signal traces be kept at least 5mm from supply lines to minimize coupling.

A variation in temperature across the PCB can cause a mismatch in the Seebeck voltages at solder joints and other points where dissimilar metals are in contact, resulting in thermal voltage errors. To minimize these thermocouple effects, orient resistors so heat sources warm both ends equally. Input signal paths should contain matching numbers and types of components, where possible to match the number and type of thermocouple junctions. For example, dummy components such as zero value resistors can be used to match real resistors in the opposite input path. Matching components should be located in close proximity and should be oriented in the same manner. Ensure leads are of equal length so that thermal conduction is in equilibrium. Keep heat sources on the PCB as far away from amplifier input circuitry as is practical.

The use of a ground plane is highly recommended. A ground plane reduces EMI noise and also helps to maintain a constant temperature across the circuit board.

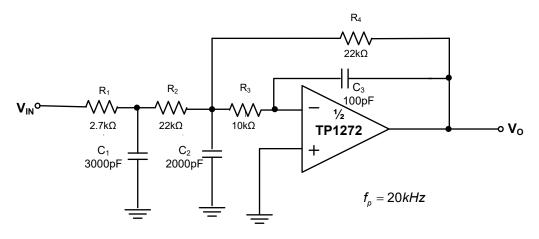


Figure 4 Three-Pole Low-Pass Filter

#### **DAC I/V Amplifier and Low-Pass Filter**

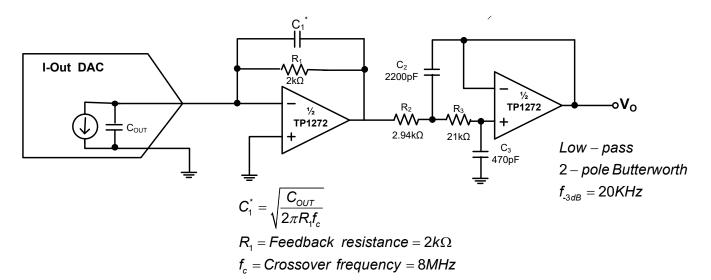
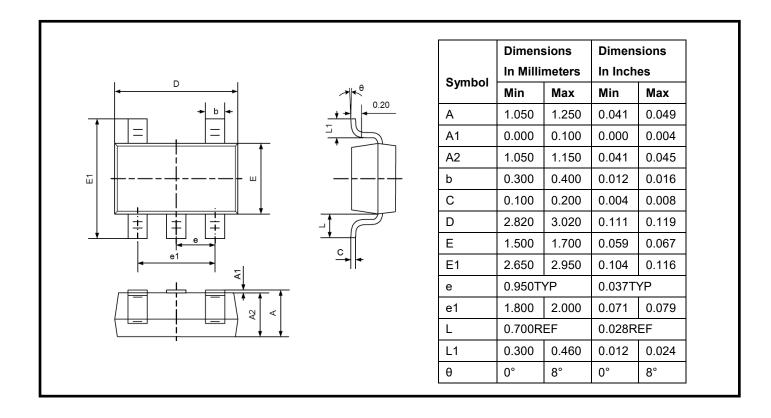


Figure 5 DAC I/V Amplifier and Low-Pass Filter

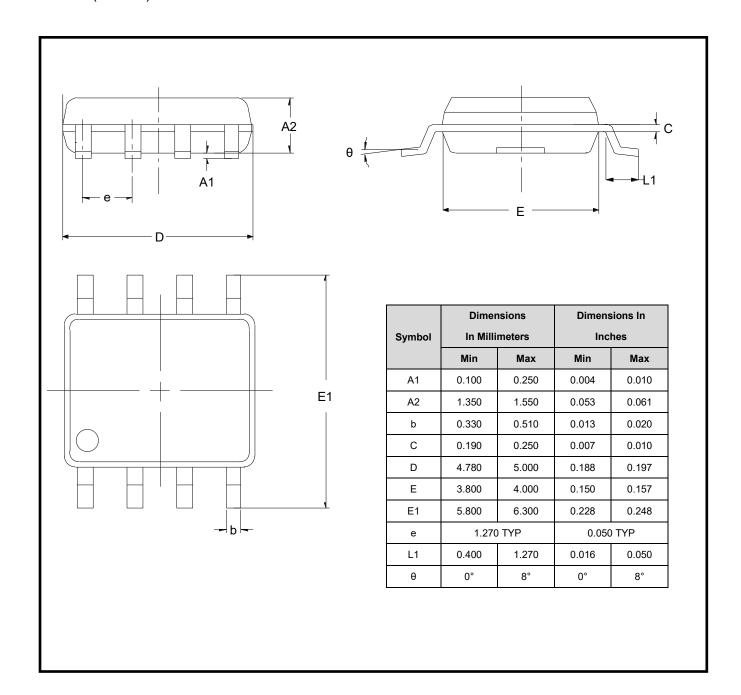
#### **Package Outline Dimensions**

SOT23-5



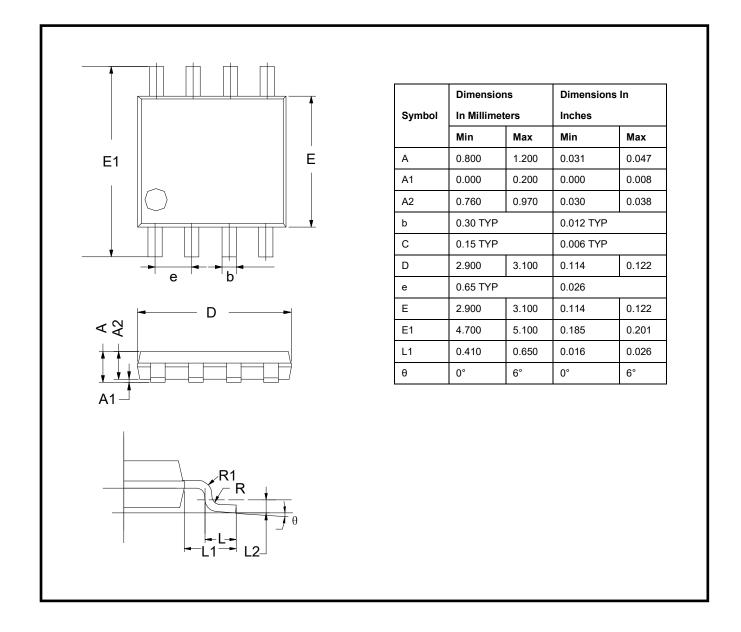
#### **Package Outline Dimensions**

SO-8 (SOIC-8)



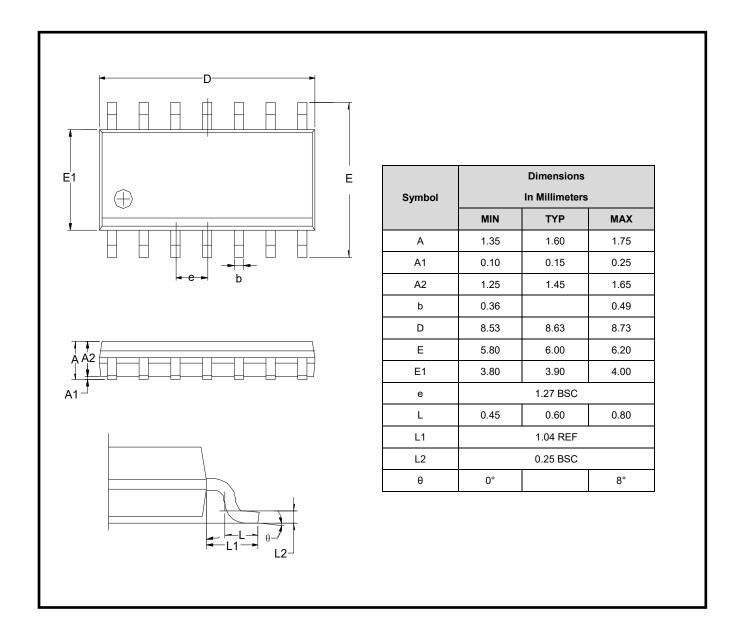
# 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth Package Outline Dimensions

MSOP-8



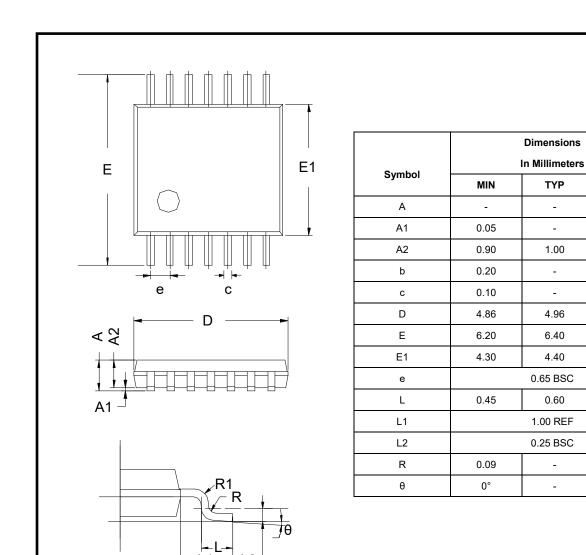
# 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth Package Outline Dimensions

SO-14 (SOIC-14)



### 36V Single supply, Precision RRO Op-amps With 7MHz Bandwidth **Package Outline Dimensions**

TSSOP-14



MAX 1.20

0.15

1.05

0.28

0.19

5.06

6.60

4.50

0.75

8°

-